

HSM198S

Silicon Schottky Barrier Diode for Various Detector

REJ03G0607-0400 (Previous: ADE-208-090C) Rev.4.00 Apr 25, 2005

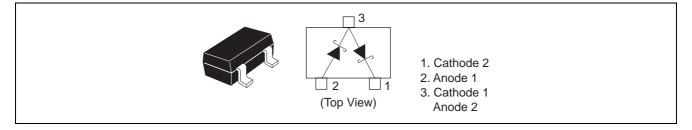
Features

- Detection efficiency is very good.
- Small temperature coefficient.
- HSM198S which is interconnected in series configuration is designed for balanced mixer use.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSM198S	C6	MPAK	PLSP0003ZC-A (MPAK)

Pin Arrangement





Absolute Maximum Ratings

	$(Ta = 25^{\circ}C)$	
Symbol	Value	Unit
V _R	10	V
I ₀ * ¹	30	mA
Тј	125	°C
Tstg	-55 to +125	°C
	V _R lo * ¹ Tj	V _R 10 Io *1 30 Tj 125

Note: 1. Two device total

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

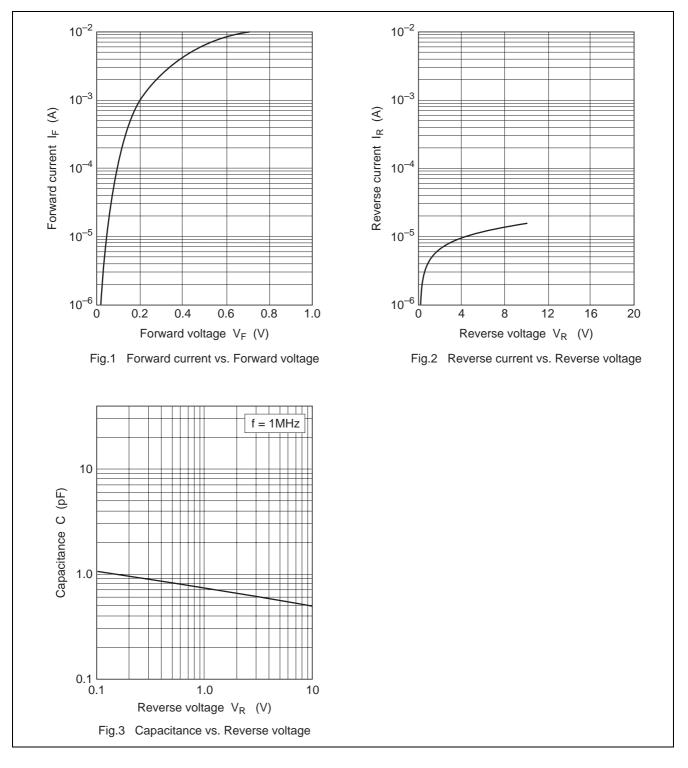
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.1	V	I _F = 5 mA
Forward current	IF	4.5	_	—	mA	V _F = 1 V
Reverse current	I _R	_	_	70	μΑ	V _R = 6 V
Capacitance	С	_	_	1.5	pF	V _R = 1 V, f = 1 MHz
Capacitance deviation	ΔV_{F}	_	_	10	mV	I _F = 5 mA
ESD Capability * ²	—	30	_	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse

Notes: 1. Per one device

2. Failure Criterrion; $I_R>140~\mu A$ at V_R = 6 V

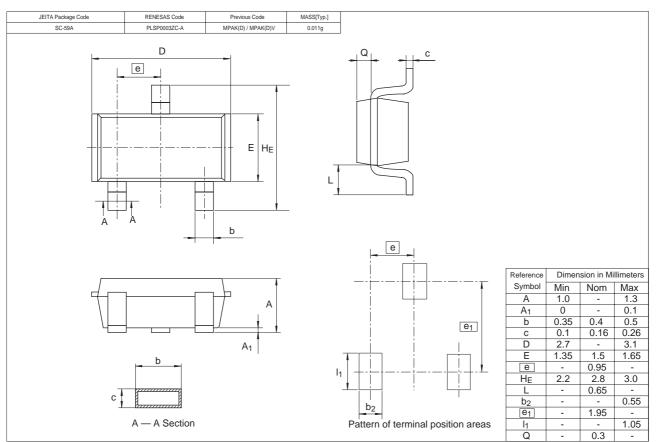


Main Characteristic





Package Dimensions





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